INTEGRATED CIRCUITS

DATA SHEET

74F02Quad 2-input NOR gate

Product specification

1990 Oct 04

IC15 Data Handbook





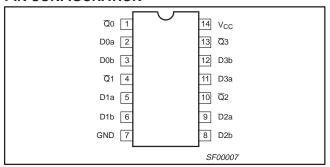
74F02

FEATURE

• Industrial temperature range available (-40°C to +85°C)

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F02	3.4ns	4.4mA

PIN CONFIGURATION



ORDERING INFORMATION

	С		
DESCRIPTION	COMMERCIAL RANGE V_{CC} = 5V ±10%, T_{amb} = 0°C to +70°C	INDUSTRIAL RANGE V_{CC} = 5V ±10%, T_{amb} = -40°C to +85°C	PKG DWG #
14-pin plastic DIP	N74F02N	174F02N	SOT27-1
14-pin plastic SO	N74F02D	I74F02D	SOT108-1

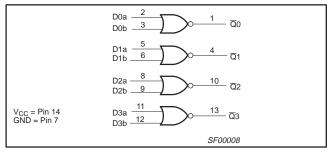
INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
Dna, Dnb	Data inputs	1.0/1.0	20μA/0.6mA
Qn	Data output	50/33	1.0mA/20mA

NOTE:

One (1.0) FAST unit load is defined as: $20\mu A$ in the high state and 0.6mA in the low state.

LOGIC DIAGRAM



FUNCTION TABLE

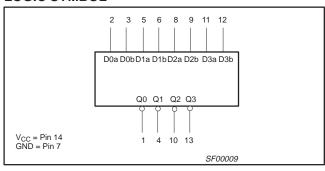
INP	JTS	OUTPUT
Dna	Dnb	Qn
L	L	Н
L	Н	L
Н	L	L
Н	Н	Ĺ

NOTES:

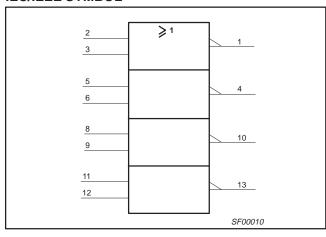
1 H = High voltage level

2 L = Low voltage level

LOGIC SYMBOL



IEC/IEEE SYMBOL



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ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free air temperature range.)

SYMBOL	PARAMETER		RATING	UNIT
V _{CC}	Supply voltage		−0.5 to +7.0	V
V _{IN}	Input voltage		-0.5 to +7.0	V
I _{IN}	Input current		−30 to +5	mA
V _{OUT}	Voltage applied to output in high output state		−0.5 to V _{CC}	V
I _{OUT}	Current applied to output in low output state		40	mA
T _{amb}	Operating free air temperature range	Commercial range	0 to +70	°C
		Industrial range	-40 to +85	°C
T _{stg}	Storage temperature range		-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER			LIMITS		UNIT
			MIN	NOM	MAX	1
V _{CC}	Supply voltage		4.5	5.0	5.5	V
V _{IH}	High-level input voltage	2.0			V	
V _{IL}	Low-level input voltage			0.8	V	
I _{lk}	Input clamp current				-18	mA
I _{OH}	High-level output current				-1	mA
I _{OL}	Low-level output current				20	mA
T _{amb}	Operating free air temperature range	Commercial range	0		+70	°C
		Industrial range	-40		+85	°C

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER		TEST CONDITIO	NS ¹		LIMITS		UNIT
					MIN	TYP ²	MAX	1
V _{OH}	High-level output voltage		$V_{CC} = MIN, V_{IL} = MAX$	±10%V _{CC}	2.5			V
			V _{IH} = MIN, I _{OH} = MAX	±5%V _{CC}	2.7	3.4		V
V _{OL}	Low-level output voltage		$V_{CC} = MIN, V_{IL} = MAX$	±10%V _{CC}		0.30	0.50	V
			$V_{IH} = MIN, I_{OI} = MAX$	±5%V _{CC}		0.30	0.50	V
V_{IK}	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$		-0.73	-1.2	V	
I _I	Input current at maximum voltage	input	$V_{CC} = MAX, V_I = 7.0V$				100	μΑ
I _{IH}	High-level input current		$V_{CC} = MAX, V_I = 2.7V$				20	μΑ
I _{IL}	Low-level input current		$V_{CC} = MAX, V_I = 0.5V$				-0.6	mA
los	Short-circuit output curren	t ³	V _{CC} = MAX		-60		-150	mA
Icc	Supply current (total) ⁴	I _{CCH}	V _{CC} = MAX			3.0	5.6	mA
		I _{CCL}	V _{CC} = MAX			7.0	13.0	mA

- For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
- All typical values are at $V_{CC} = 5V$, $T_{amb} = 25^{\circ}C$. Not more than one output should be shorted at a time. For testing I_{OS} , the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

I_{CC} is measured with outputs open.

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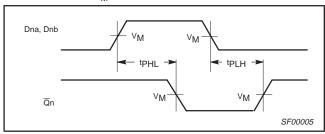
SF00006

AC ELECTRICAL CHARACTERISTICS

	PARAMETER			LIMITS						
SYMBOL		TEST CONDITION	V_{CC} = +5.0V T_{amb} = +25°C C_L = 50pF, R_L = 500 Ω			T _{amb} = 0°0	0V ± 10% C to +70°C R _L = 500Ω	$V_{CC} = +5.$ $T_{amb} = -40^{\circ}$ $C_{L} = 50 pF$,	UNIT	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	Propagation delay Dna, Dnb to Qn	Waveform 1	2.5 2.0	4.4 3.2	5.5 4.3	2.5 2.0	6.5 5.3	2.5 1.5	7.0 6.0	ns

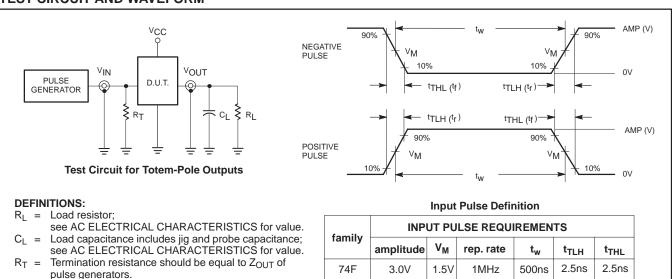
AC WAVEFORMS

For all waveforms, $V_M = 1.5V$.



Waveform 1. Propagation delay for inverting outputs

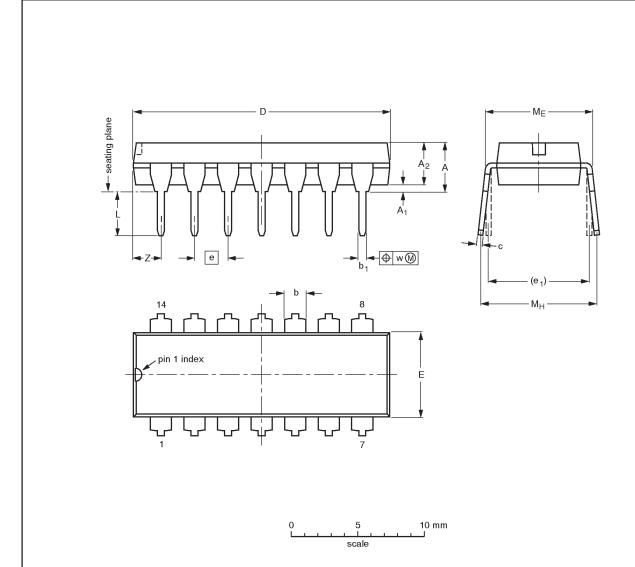
TEST CIRCUIT AND WAVEFORM



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DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	Мн	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

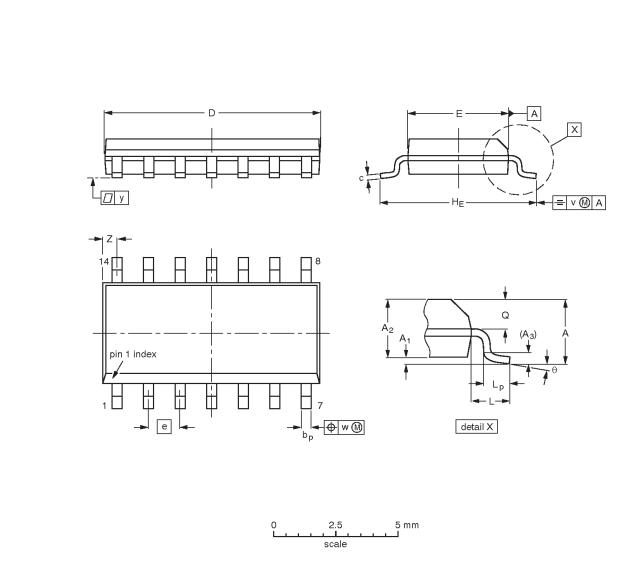
OUTLINE		REFER		EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	PROJECTION	ISSUE DATE		
SOT27-1	050G04	MO-001AA				92-11-17 95-03-11

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74F02

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075		0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	PROJECTION	ISSUE DATE		
SOT108-1	076E06S	MS-012AB			-95-01-23- 97-05-22	

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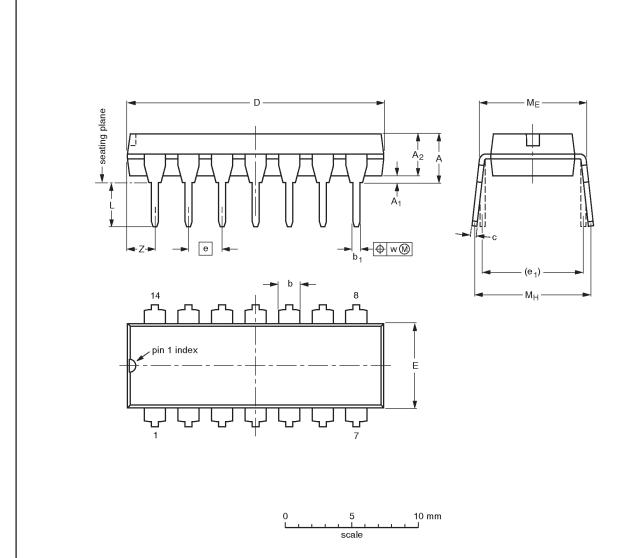
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DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	С	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	Мн	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

Note

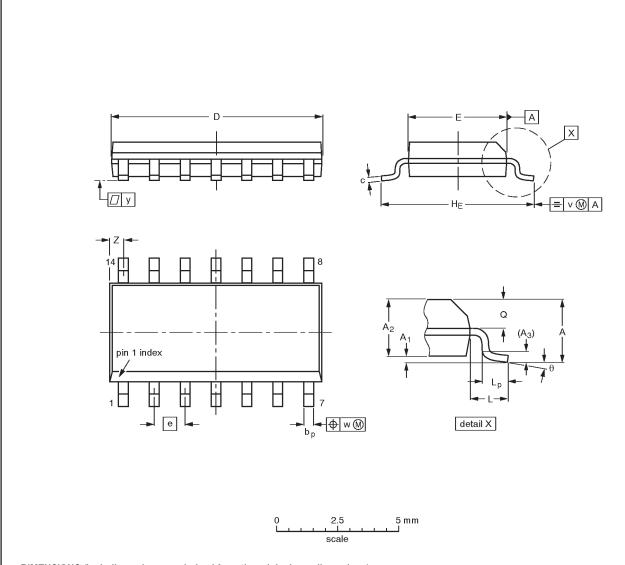
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OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT27-1	050G04	MO-001AA				92-11-17 95-03-11

74F02

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Ø	v	w	у	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.0098 0.0039	0.057 0.049	0.01		0.0098 0.0075		0.16 0.15	0.050	0.24 0.23	0.041	0.039 0.016		0.01	0.01	0.004	0.028 0.012	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFEF	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT108-1	076E06S	MS-012AB				91-08-13 95-01-23

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NOTES

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	DEFINITIONS								
Data Sheet Identification	Product Status	Definition							
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.							
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Phillips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.							
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